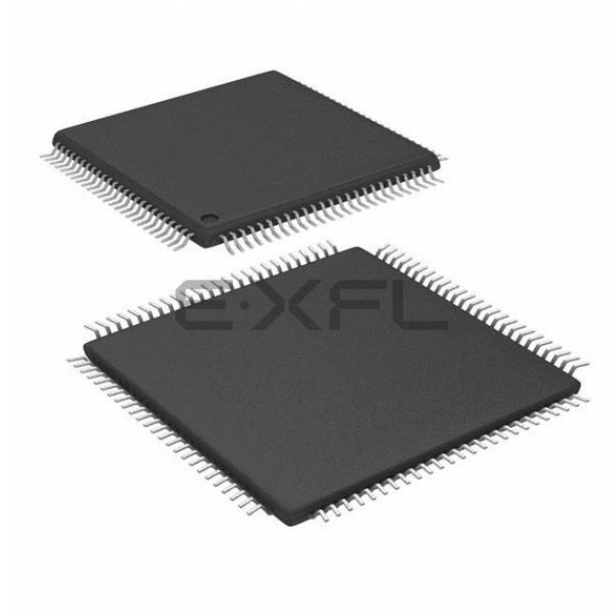
Microchip Technology - PIC32MX350F128LT-I/PT Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx350f128lt-i-pt

Referenced Sources

This device data sheet is based on the following individual sections of the *"PIC32 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note: To access the following documents, refer to the *Documentation > Reference Manuals* section of the Microchip PIC32 website: http://www.microchip.com/pic32.

- **Section 1. "Introduction"** (DS60001127)
- **Section 2. "CPU"** (DS60001113)
- **Section 3. "Memory Organization"** (DS60001115)
- **Section 4. "Prefetch Cache"** (DS60001119)
- **Section 5. "Flash Program Memory"** (DS60001121)
- **Section 6. "Oscillator Configuration"** (DS60001112)
- **Section 7. "Resets"** (DS60001118)
- **Section 8. "Interrupt Controller"** (DS60001108)
- **Section 9. "Watchdog Timer and Power-up Timer"** (DS60001114)
- **Section 10. "Power-Saving Features"** (DS60001130)
- **Section 12. "I/O Ports"** (DS60001120)
- **Section 13. "Parallel Master Port (PMP)"** (DS60001128)
- **Section 14. "Timers"** (DS60001105)
- **Section 15. "Input Capture"** (DS60001122)
- **Section 16. "Output Compare"** (DS60001111)
- **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104)
- **Section 19. "Comparator"** (DS60001110)
- **Section 20. "Comparator Voltage Reference (CV_{REF})"** (DS60001109)
- **Section 21. "Universal Asynchronous Receiver Transmitter (UART)"** (DS60001107)
- **Section 23. "Serial Peripheral Interface (SPI)"** (DS60001106)
- **Section 24. "Inter-Integrated Circuit (I^2C)"** (DS60001116)
- **Section 27. "USB On-The-Go (OTG)"** (DS60001126)
- **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125)
- **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117)
- **Section 32. "Configuration"** (DS60001124)
- **Section 33. "Programming and Diagnostics"** (DS60001129)
- **Section 37. "Charge Time Measurement Unit (CTMU)"** (DS60001167)

REGISTER 6-1: RCON: RESET CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	—	—	HVDR	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS	R/W-0
	—	—	—	—	—	—	CMR	VREGS
7:0	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-1, HS	R/W-1, HS
	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR(1)	POR(1)

Legend:	HS = Set by hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29 **HVDR:** High Voltage Detect Reset Flag bit
1 = High Voltage Detect (HVD) Reset has occurred
0 = HVD Reset has not occurred

bit 28-10 **Unimplemented:** Read as '0'

bit 9 **CMR:** Configuration Mismatch Reset Flag bit
1 = Configuration mismatch Reset has occurred
0 = Configuration mismatch Reset has not occurred

bit 8 **VREGS:** Voltage Regulator Standby Enable bit
1 = Regulator is enabled and is on during Sleep mode
0 = Regulator is set to Stand-by Tracking mode

bit 7 **EXTR:** External Reset ($\overline{MCLR}$) Pin Flag bit
1 = Master Clear (pin) Reset has occurred
0 = Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset Flag bit
1 = Software Reset was executed
0 = Software Reset as not executed

bit 5 **Unimplemented:** Read as '0'

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT Time-out has occurred
0 = WDT Time-out has not occurred

bit 3 **SLEEP:** Wake From Sleep Flag bit
1 = Device was in Sleep mode
0 = Device was not in Sleep mode

bit 2 **IDLE:** Wake From Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit(1)
1 = Brown-out Reset has occurred
0 = Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit(1)
1 = Power-on Reset has occurred
0 = Power-on Reset has not occurred

Note 1: User software must clear this bit to view next detection.

10.0 DIRECT MEMORY ACCESS (DMA) CONTROLLER

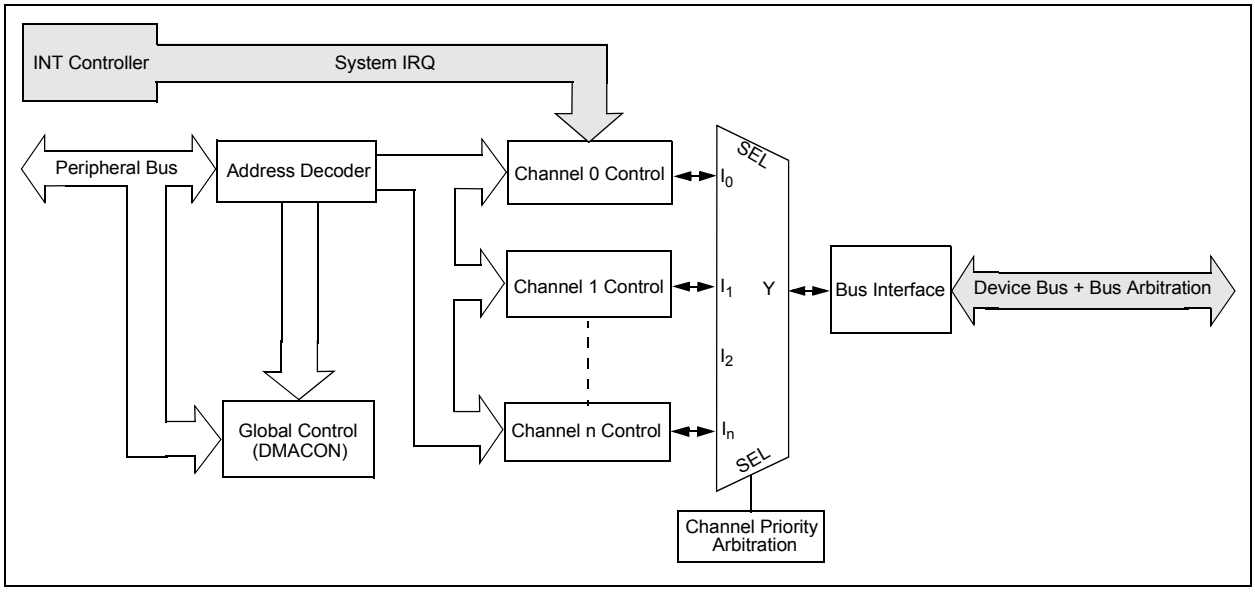
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 Direct Memory Access (DMA) controller is a bus master module useful for data transfers between different devices without CPU intervention. The source and destination of a DMA transfer can be any of the memory mapped modules existent in the PIC32 (such as Peripheral Bus (PBUS) devices: SPI, UART, PMP, etc.) or memory itself.

Following are some of the key features of the DMA controller module:

- Four identical channels, each featuring:
  - Auto-increment source and destination address registers
  - Source and destination pointers
  - Memory to memory and memory to peripheral transfers
- Automatic word-size detection:
  - Transfer granularity, down to byte level
  - Bytes need not be word-aligned at source and destination
- Fixed priority channel arbitration
- Flexible DMA channel operating modes:
  - Manual (software) or automatic (interrupt) DMA requests
  - One-Shot or Auto-Repeat Block Transfer modes
  - Channel-to-channel chaining
- Flexible DMA requests:
  - A DMA request can be selected from any of the peripheral interrupt sources
  - Each channel can select any (appropriate) observable interrupt as its DMA request source
  - A DMA transfer abort can be selected from any of the peripheral interrupt sources
  - Pattern (data) match transfer termination
- Multiple DMA channel status interrupts:
  - DMA channel block transfer complete
  - Source empty or half empty
  - Destination full or half full
  - DMA transfer aborted due to an external event
  - Invalid DMA address generated
- DMA debug support features:
  - Most recent address accessed by a DMA channel
  - Most recent DMA channel to transfer data
- CRC Generation module:
  - CRC module can be assigned to any of the available channels
  - CRC module is highly configurable

FIGURE 10-1: DMA BLOCK DIAGRAM



REGISTER 10-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER (CONTINUED)

bit 4 **CHDHIF:** Channel Destination Half Full Interrupt Flag bit
- 1 = Channel Destination Pointer has reached midpoint of destination (CHDPTR = CHDSIZ/2)
- 0 = No interrupt is pending

bit 3 **CHBCIF:** Channel Block Transfer Complete Interrupt Flag bit
- 1 = A block transfer has been completed (the larger of CHSSIZ/CHDSIZ bytes has been transferred), or a pattern match event occurs
- 0 = No interrupt is pending

bit 2 **CHCCIF:** Channel Cell Transfer Complete Interrupt Flag bit
- 1 = A cell transfer has been completed (CHCSIZ bytes have been transferred)
- 0 = No interrupt is pending

bit 1 **CHTAIF:** Channel Transfer Abort Interrupt Flag bit
- 1 = An interrupt matching CHAIRQ has been detected and the DMA transfer has been aborted
- 0 = No interrupt is pending

bit 0 **CHERIF:** Channel Address Error Interrupt Flag bit
- 1 = A channel address error has been detected
  Either the source or the destination address is invalid.
- 0 = No interrupt is pending

TABLE 12-1: INPUT PIN SELECTION (CONTINUED)

Peripheral Pin	[*pin name*]R SFR	[*pin name*]R bits	[*pin name*]R Value to RPn Pin Selection
INT1	INT1R	INT1R<3:0>	0000 = RPD1 0001 = RPG9 0010 = RPB14 0011 = RPD0 0100 = RPD8 0101 = RPB6 0110 = RPD5 0111 = RPB2 1000 = RPF3(4) 1001 = RPF13(3) 1010 = Reserved 1011 = RPF2(1) 1100 = RPC2(3) 1101 = RPE8(3) 1110 = Reserved 1111 = Reserved
T3CK	T3CKR	T3CKR<3:0>	
IC1	IC1R	IC1R<3:0>	
$\overline{\text{U3CTS}}$	U3CTSR	U3CTSR<3:0>	
U4RX	U4RXR	U4RXR<3:0>	
U5RX	U5RXR(3)	U5RXR<3:0>	
$\overline{\text{SS2}}$	SS2R	SS2R<3:0>	
OCFA	OCFAR	OCFAR<3:0>	

Note 1: This selection is not available on 64-pin USB devices.

2: This selection is only available on 100-pin General Purpose devices.

3: This selection is not available on 64-pin USB and General Purpose devices.

4: This selection is only available on General Purpose devices.

TABLE 12-5: PORTC REGISTER MAP FOR PIC32MX330F064L, PIC32MX350F128L, PIC32MX350F256L, PIC32MX370F512L, PIC32MX430F064L, PIC32MX450F128L, PIC32MX450F256L, AND PIC32MX470F512L DEVICES ONLY

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6210	TRISC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISC15	TRISC14	TRISC13	TRISC12	—	—	—	—	—	—	—	TRISC4	TRISC3	TRISC2	TRISC1	—	xxxx
6220	PORTC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RC15	RC14	RC13	RC12	—	—	—	—	—	—	—	RC4	RC3	RC2	RC1	—	xxxx
6230	LATC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATC15	LATC14	LATC13	LATC12	—	—	—	—	—	—	—	LATC4	LATC3	LATC2	LATC1	—	xxxx
6240	ODCC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCC15	ODCC14	ODCC13	ODCC12	—	—	—	—	—	—	—	ODCC4	ODCC3	ODCC2	ODCC1	—	xxxx
6250	CNPUC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPUC15	CNPUC14	CNPUC13	CNPUC12	—	—	—	—	—	—	—	CNPUC4	CNPUC3	CNPUC2	CNPUC1	—	xxxx
6260	CNPDC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPDC15	CNPDC14	CNPDC13	CNPDC12	—	—	—	—	—	—	—	CNPDC4	CNPDC3	CNPDC2	CNPDC1	—	xxxx
6270	CNCONC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6280	CNENC	31:16	—	—		—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNIEC15	CNIEC14	CNIEC13	CNIEC12	—	—	—	—	—	—	—	CNIEC4	CNIEC3	CNIEC2	CNIEC1	—	xxxx
6290	CNSTATC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNSTATC15	CNSTATC14	CNSTATC13	CNSTATC12	—	—	—	—	—	—	—	CNSTATC4	CNSTATC3	CNSTATC2	CNSTATC1	—	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

15.0 WATCHDOG TIMER (WDT)

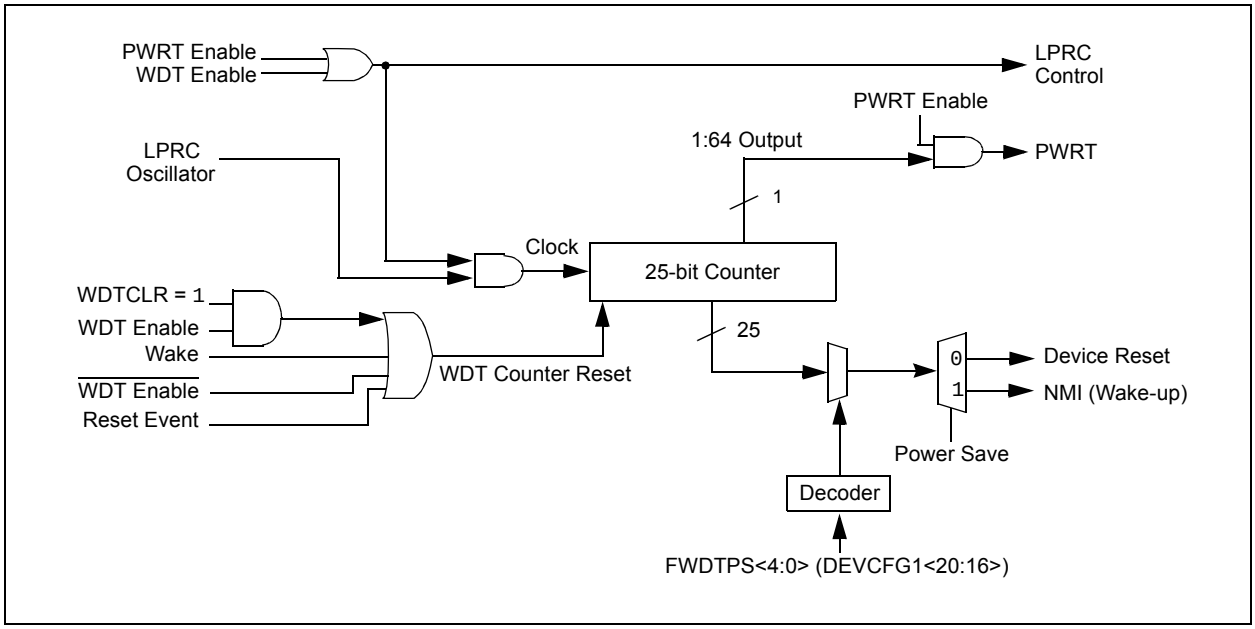
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog, Deadman, and Power-up Timers"** (DS60001114), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The WDT, when enabled, operates from the internal Low-Power Oscillator (LPRC) clock source and can be used to detect system software malfunctions by resetting the device if the WDT is not cleared periodically in software. Various WDT time-out periods can be selected using the WDT postscaler. The WDT can also be used to wake the device from Sleep or Idle mode.

The following are some of the key features of the WDT module:

- Configuration or software controlled
- User-configurable time-out period
- Can wake the device from Sleep or Idle

FIGURE 15-1: WATCHDOG AND POWER-UP TIMER BLOCK DIAGRAM



15.1 Watchdog Timer Control Registers

TABLE 15-1: WATCHDOG TIMER CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0000	WDTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	SWDTPS<4:0>					WDTWINEN	WDTCLR	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

18.1 Control Registers

TABLE 18-1: SPI2 AND SPI2 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5800	SPI1CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>		0000
5810	SPI1STAT	31:16	—	—	—	RXBUFELM<4:0>					—	—	—	TXBUFELM<4:0>					0000
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	19EB
5820	SPI1BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5830	SPI1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	BRG<8:0>									0000
5840	SPI1CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>		0000
5A00	SPI2CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>		0000
5A10	SPI2STAT	31:16	—	—	—	RXBUFELM<4:0>					—	—	—	TXBUFELM<4:0>					0000
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	19EB
5A20	SPI2BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5A30	SPI2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	BRG<8:0>									0000
5A40	SPI2CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 22-2: RTCALRM: RTC ALARM CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	ALRMEN(1,2)	CHIME(2)	PIV(2)	ALRMSYNC(3)	AMASK<3:0>(3)			
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ARPT<7:0>(3)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ALRMEN:** Alarm Enable bit(1,2)
- 1 = Alarm is enabled
- 0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit(2)
- 1 = Chime is enabled – ARPT<7:0> is allowed to rollover from 0x00 to 0xFF
- 0 = Chime is disabled – ARPT<7:0> stops once it reaches 0x00

bit 13 **PIV:** Alarm Pulse Initial Value bit(2)

When ALRMEN = 0, PIV is writable and determines the initial value of the Alarm Pulse.
When ALRMEN = 1, PIV is read-only and returns the state of the Alarm Pulse.

bit 12 **ALRMSYNC:** Alarm Sync bit(3)
- 1 = ARPT<7:0> and ALRMEN may change as a result of a half second rollover during a read. The ARPT must be read repeatedly until the same value is read twice. This must be done since multiple bits may be changing, which are then synchronized to the PB clock domain
- 0 = ARPT<7:0> and ALRMEN can be read without concerns of rollover because the prescaler is > 32 RTC clocks away from a half-second rollover

bit 11-8 **AMASK<3:0>:** Alarm Mask Configuration bits(3)
- 0000 = Every half-second
- 0001 = Every second
- 0010 = Every 10 seconds
- 0011 = Every minute
- 0100 = Every 10 minutes
- 0101 = Every hour
- 0110 = Once a day
- 0111 = Once a week
- 1000 = Once a month
- 1001 = Once a year (except when configured for February 29, once every four years)
- 1010 = Reserved; do not use
- 1011 = Reserved; do not use
- 11xx = Reserved; do not use

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note: This register is reset only on a Power-on Reset (POR).

24.1 Control Registers

TABLE 24-1: COMPARATOR REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
A000	CM1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		E1C3
A010	CM2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		E1C3
A060	CMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	C2OUT	C1OUT	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control edge source
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 23 **EDG2MOD:** Edge 2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 programmed for a positive edge response
0 = Edge 2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = Reserved
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-42) in **Section 31.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

29.0 INSTRUCTION SET

The PIC32MX330/350/370/430/450/470 family instruction set complies with the MIPS32® Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

Note: Refer to *"MIPS32® Architecture for Programmers Volume II: The MIPS32® Instruction Set"* at www.imgtec.com for more information.

TABLE 31-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Parameter No.	**Typical(3)**	**Maximum**	**Units**	**Conditions**	
Operating Current (IDD)(1,2)					
DC20	2.5	4	mA	4 MHz	
DC21	6	9	mA	10 MHz **(Note 4)**	
DC22	11	17	mA	20 MHz **(Note 4)**	
DC23	21	32	mA	40 MHz **(Note 4)**	
DC24	30	45	mA	60 MHz **(Note 4)**	
DC25	40	60	mA	80 MHz	
DC25a	50	75	mA	100 MHz, -40°C ≤ TA ≤ +85°C	
DC25c	72	84	mA	120 MHz, 0°C ≤ TA ≤ +70°C	
DC26	100	—	µA	+25ºC, 3.3V	LPRC (31 kHz) **(Note 4)**

Note 1: A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for IDD measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, program Flash, and SRAM data memory are operational, program Flash memory Wait states = 7, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating (ON bit = 0), but the associated PMD bit is clear
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- CPU executing `while(1)` statement from Flash
- RTCC and JTAG are disabled

3: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

4: This parameter is characterized, but not tested in manufacturing.

TABLE 31-10: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.(1)**	**Typical**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low	2.0	—	2.3	V	—

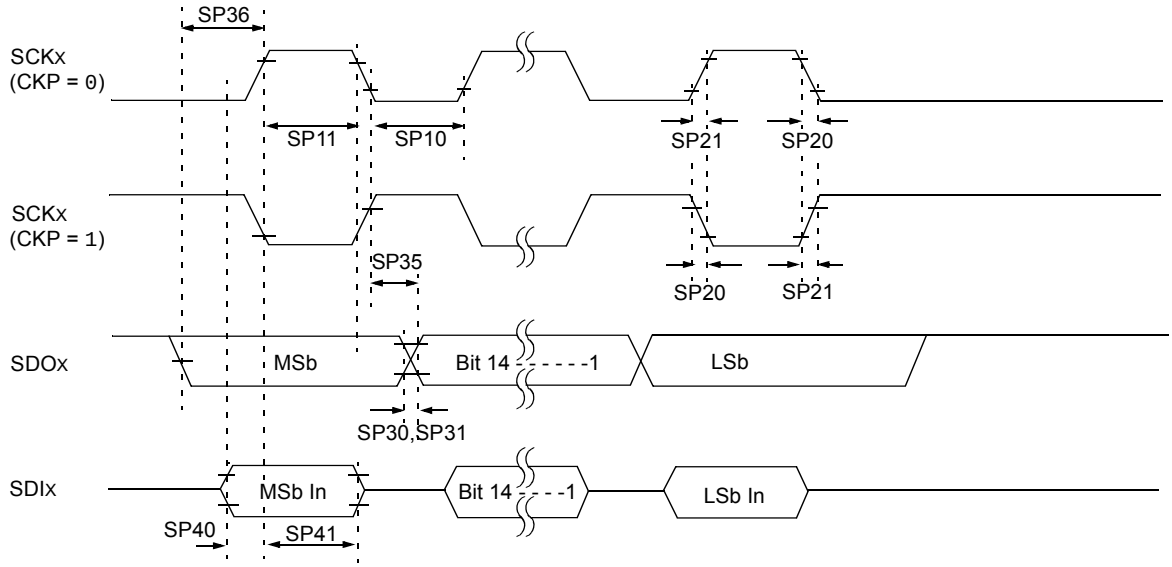
Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 31-11: ELECTRICAL CHARACTERISTICS: HVD

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.(1)	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
HV10	VHVD	High Voltage Detect on VCAP pin	—	2.5	—	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

FIGURE 31-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-30: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 31-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

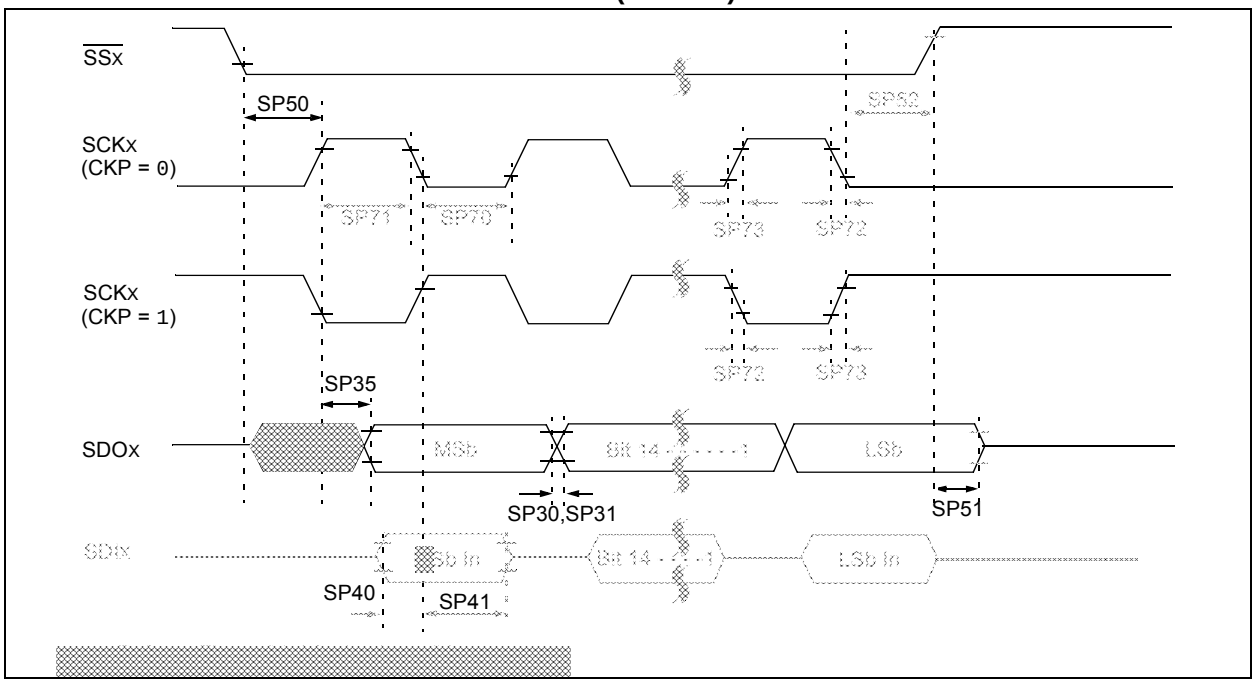


TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 3)**	5	—	25	ns	—

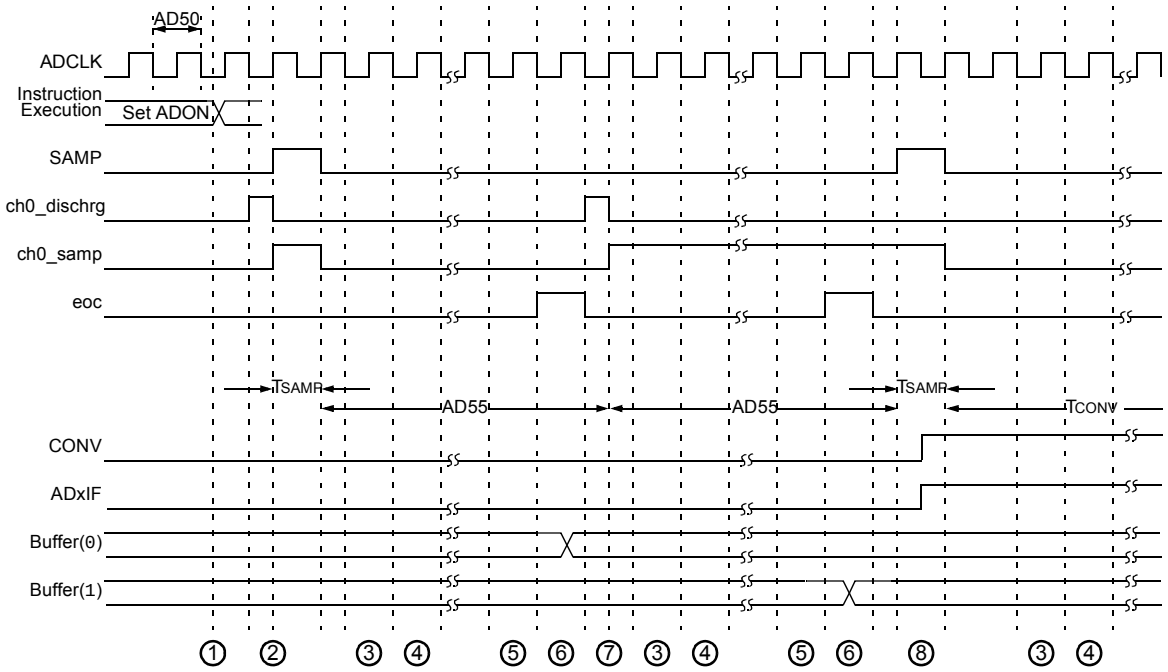
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 31-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period.
TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104) in the *"PIC32 Family Reference Manual"*

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

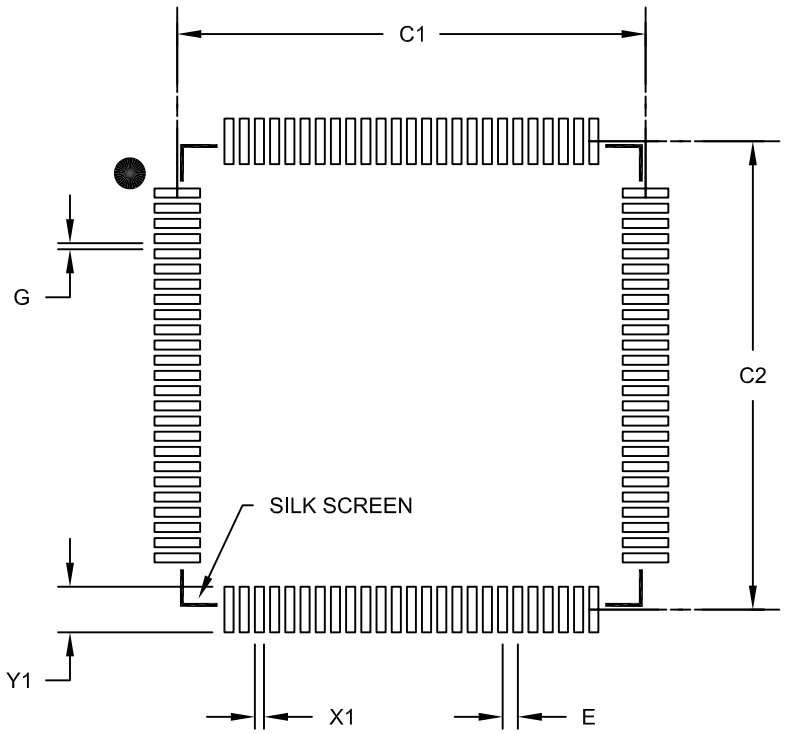
(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B

NOTES: